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(12) **United States Design Patent**
Liu

(10) **Patent No.:** **US D602,445 S**

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(54) **LOGIC MODULE**

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(**) **Term:** **14 Years**

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D13/159, 160, 162, 162.1, 163, 164, 177,
D13/178, 184, 199; D10/106; 439/660,
439/568; 361/686, 752, 600, 601, 627, 641,
361/690, 678, 605; 307/149, 125, 113; 232/4 R,
232/1 D; 220/324, 3.8; 109/173; 206/1.5

See application file for complete search history.

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(57) **CLAIM**

I claim the ornamental design for a logic module, as shown and described.

DESCRIPTION

FIG. 1 is a topview of the logic module; and,
FIG. 2 is a side view of the logic module.

1 Claim, 2 Drawing Sheets

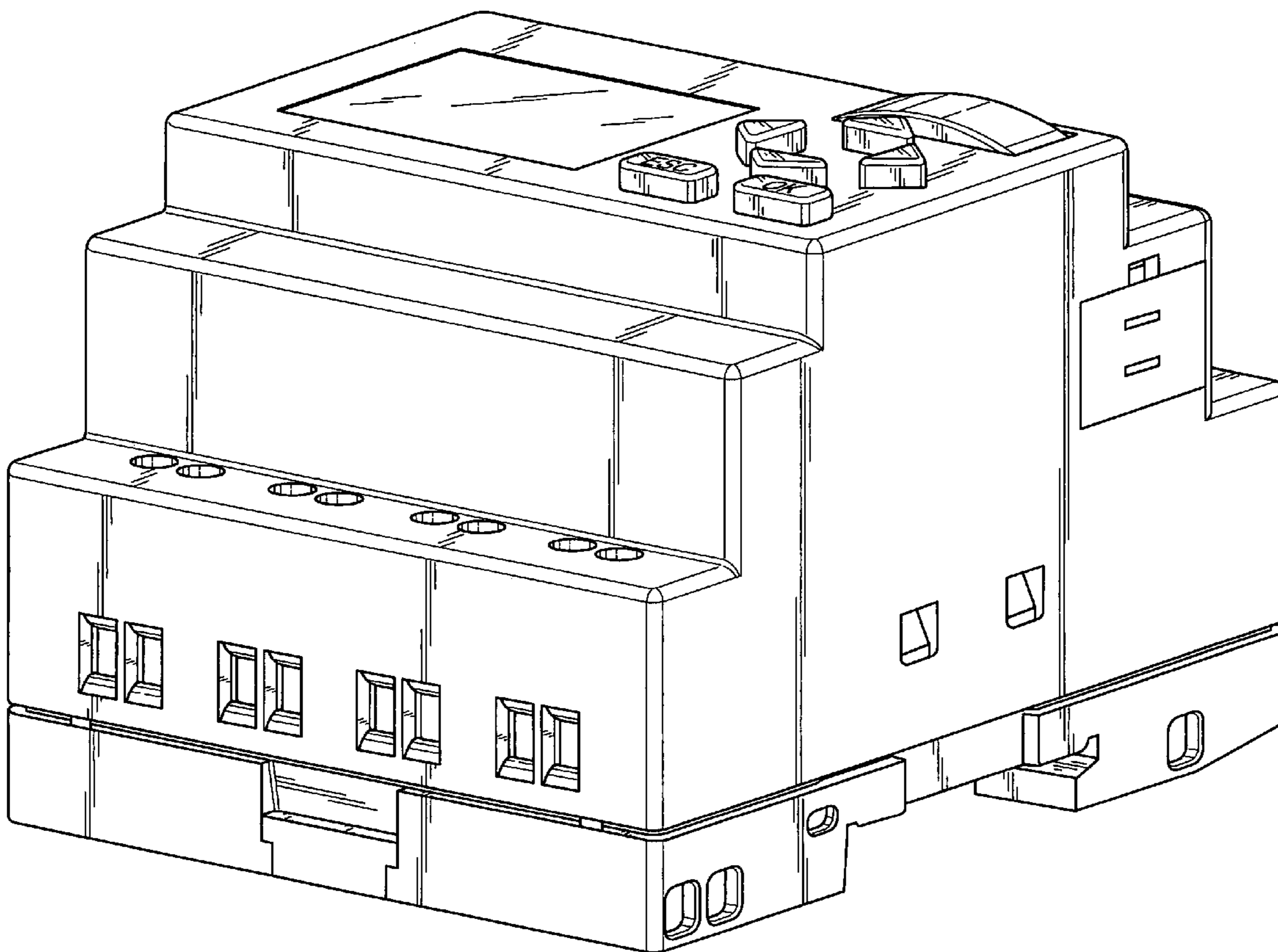


FIG 1

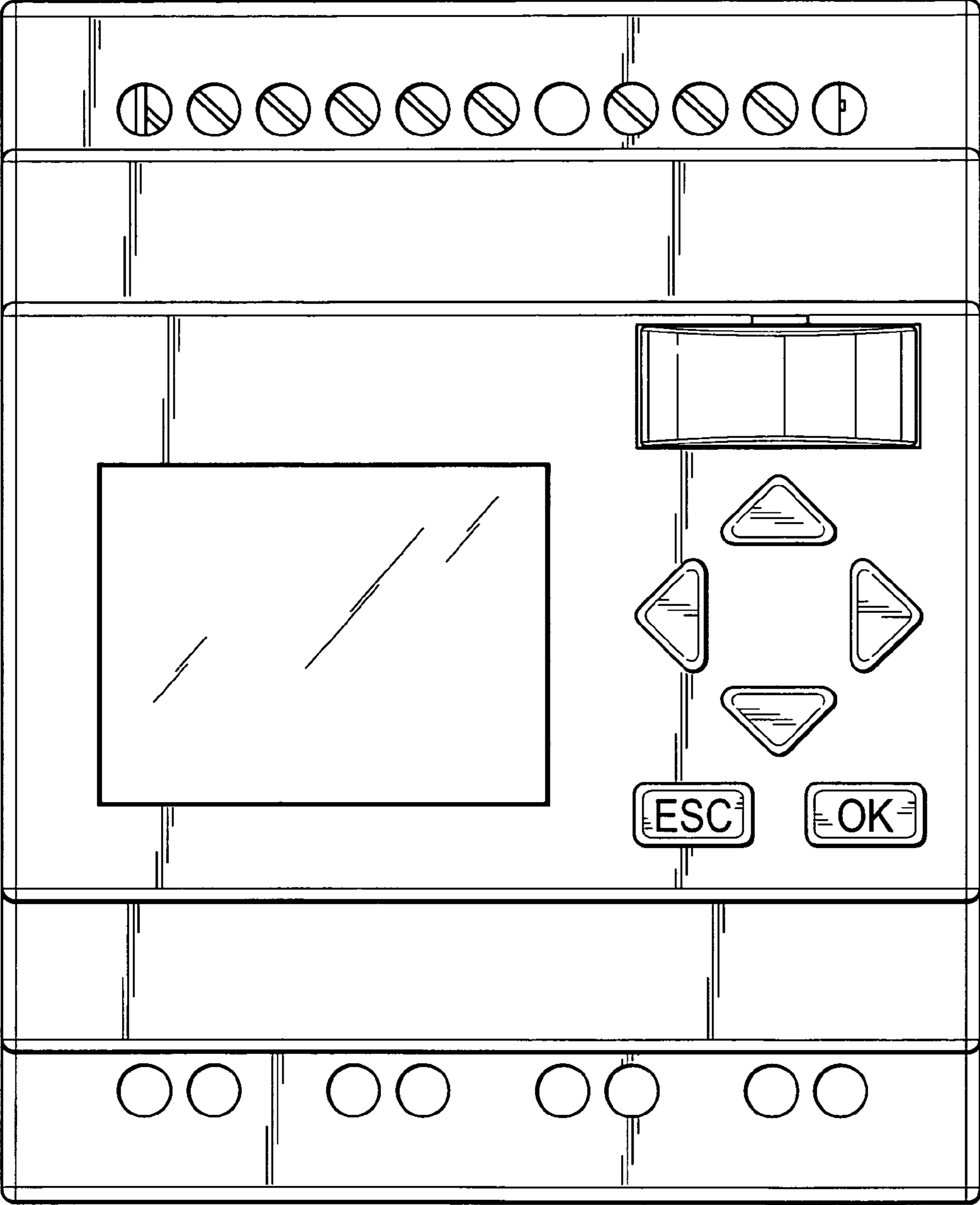


FIG 2

